

VLSI Design (BEC-41) (Unit-1, Lecture-6)



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16-07-2020 Side 1

Introduction

- The SPICE software that was distributed by UC Berkeley beginning in the late 1970s had three built-in MOSFET models
 - LEVEL1(MOS1) is a described y a square-law current-voltage characteristics
 - LEVEL2 (MOS2) is a detailed analytical MOSFET model
 - LEVEL 3 (MOS3) is a semi-empirical model
 - Both MOS2 and MOS3 include second-order effects
 - The short channel threshold voltage, subthreshold conduction, scattering-limited velocity saturation, and charge-controlled capacitances
 - The BSIM3 version
 - More accurate characterization sub-micron MOSFET characteristics



Basic concept

 The equivalent circuit structure of the NMOS LEVEL 1 model

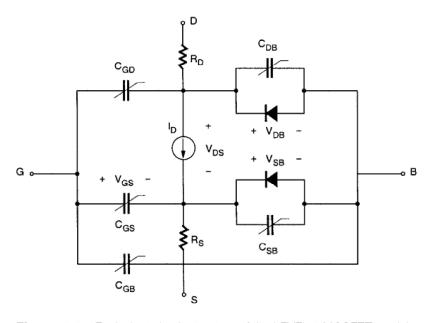


Figure 4.1 Equivalent circuit structure of the LEVEL 1 MOSFET model in SPICE.



The LEVEL 1 model equation

Linear region

$$I_{D} = \frac{k'}{2} \cdot \frac{W}{L_{eff}} \cdot \left[2 \cdot (V_{GS} - V_{T}) V_{DS} - V_{DS}^{2} \right] \cdot (1 + \lambda \cdot V_{DS}) for \quad V_{GS} \ge V_{T}$$
• $\gamma = 0.53 V^{1/2}$
• $2\phi F = -0.58$

and $V_{DS} < V_{GS} - V_T$ • $\lambda = 0$

Saturation region

$$I_{D} = \frac{k'}{2} \cdot \frac{W}{L_{eff}} \cdot (V_{GS} - V_{T})^{2} \cdot (1 + \lambda \cdot V_{DS}) for \quad V_{GS} \ge V_{T}$$

and $V_{DS} \ge V_{GS} - V_T$

The threshold voltage

$$V_T = V_{T0} + \gamma \cdot \left(\sqrt{\left| 2\phi_F \right| + V_{SB}} - \sqrt{\left| 2\phi_F \right|} \right)$$

$$L_{\it eff} = L - 2 \cdot L_{\it D}$$

$$k' = \mu \cdot C_{ox}$$
 where $C_{ox} = \frac{\varepsilon_{ox}}{t_{ox}}$

$$\gamma = \frac{\sqrt{2 \cdot \varepsilon_{Si} \cdot q \cdot N_A}}{C_{cor}}$$

$$2\phi_F = 2\frac{kT}{q} \cdot \ln\left(\frac{n_i}{N_A}\right)$$

•
$$\gamma = 0.53 V^{1/2}$$
 GAMMA=0.53

UO=800

NSUB=1E15

$$\lambda$$
=0 LAMBDA=0

•
$$\mu_n = 800 \text{ cm}^2/\text{Vs}$$

•
$$t_{ox}$$
=100nm TOX=100E-9

•
$$N_A^{=}=10^{15} cm^{-3}$$



Variation of the drain current with model parameter

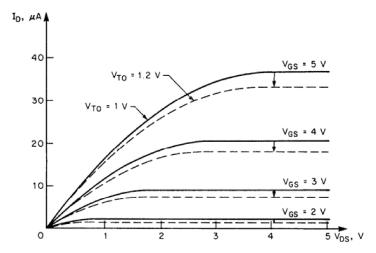


Figure 4.2 Variation of the drain current with model parameter VTO, for the LEVEL 1 model.

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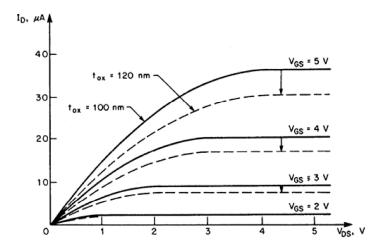


Figure 4.4 Variation of the drain current with model parameter TOX, for the LEVEL 1 model.

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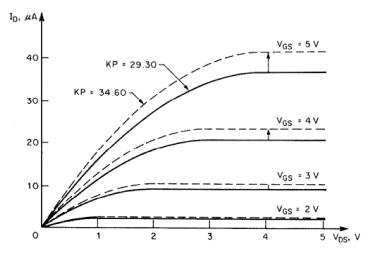


Figure 4.3 Variation of the drain current with model parameter KP, for the LEVEL 1 model.

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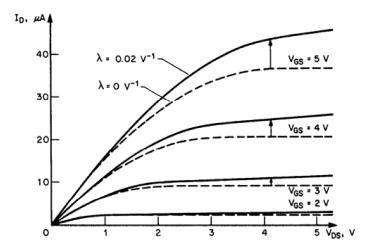


Figure 4.5 Variation of the drain current with parameter LAMBDA, for the LEVEL 1 model.

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The LEVEL 2 model equation

$$I_{D} = \frac{k'}{\left(1 - \lambda \cdot V_{DS}\right)} \cdot \frac{W}{L_{eff}} \cdot \left\{ \left(V_{GS} - V_{FB} - \left|2\phi_{F}\right| - \frac{V_{DS}}{2}\right) \cdot V_{DS} - \frac{2}{3} \cdot \gamma \cdot \left[\left(V_{DS} - V_{BS} + \left|2\phi_{F}\right|\right)^{3/2} - \left(-V_{BS} + \left|2\phi_{F}\right|\right)^{3/2}\right] \right\}$$

The saturation voltage

$$V_{DSAT} = V_{GS} - V_{FB} - |2\phi_F| + \gamma^2 \cdot \left(1 - \sqrt{1 + \frac{2}{\gamma^2} \cdot (V_{GS} - V_{FB})}\right)$$

The saturation mode current

$$I_D = I_{Dsat} \cdot \frac{1}{\left(1 - \lambda \cdot V_{DS}\right)}$$

The zero bias threshold voltage

$$V_{T0} = \Phi_{GC} - \frac{q \cdot N_{ss}}{C_{ox}} + \left| 2\phi_F \right| + \gamma \sqrt{\left| 2\phi_F \right|}$$

- In the current equation above, the surface carrier mobility has been assumed constant, and its variation with applied terminal voltages has been neglected
- In reality, the surface mobility decreases with the increasing gate voltage
 - Due to the scattering of carriers in the channel

$$k'_{(new)} = k' \cdot \left(\frac{\varepsilon_{Si}}{\varepsilon_{ox}} \cdot \frac{t_{oc} \cdot U_{c}}{\left(V_{GS} - V_{T} - U_{t} \cdot V_{DS}\right)}\right)^{Ue}$$

 U_c is the gate - to - channel critical field

 U_t is the contribution of the drain voltage to the gate - to - channel field

 U_e is the exponential fitting parameter



variation of channel length in saturation mode

$$\begin{split} \dot{L_{eff}} &= L_{eff} - \Delta L \\ \Delta L &= \sqrt{\frac{2 \cdot \varepsilon_{Si}}{q \cdot N_A}} \cdot \left[\frac{V_{DS} - V_{DSAT}}{4} + \sqrt{1 + \left(\frac{V_{DS} - V_{DSAT}}{4}\right)^2} \right] \end{split}$$

The empirical channel length shortening coefficient

$$\lambda = \frac{\Delta L}{L_{\it eff} \cdot V_{\it DS}}$$

The slope of the I_D - V_{DS} vurve is saturation can be adjusted and fitted to experimental data by changing the substrate doping parameter N_A In this case, however, other N_A - dependent electrical parameters such as $2\phi_F$ and γ must be specified separately in the .MODEL statement



Saturation of carrier velocity

- The calculation of the saturation voltage V_{DSAT} is based on the assumption
 - The channel charge near the drain becomes equal to zero when the device enters saturation
 - This hypothesis is actually incorrect
 - Since a minimum charge concentration greater than zero must exist in the channel, due to the carriers that sustain the saturation current
 - The minimum concentration depends on the speed of the carriers
 - The inversion layer charge at the channel-end is found as

$$Q_{inv} = \frac{I_{Dsat}}{W \cdot v_{max}}$$

$$\Delta L = X_D \cdot \sqrt{\left(\frac{X_D \cdot v_{max}}{2 \cdot \mu}\right)^2 + V_{DS} - V_{DSAT}} - \frac{X_D^2 \cdot v_{max}}{2 \cdot \mu}$$

$$X_D = \sqrt{\frac{2 \cdot \varepsilon_{Si}}{q \cdot N_A \cdot N_{eff}}}$$

The parameter N_{eff} is used as a fitting parameter



Subthreshold conduction

- For V_{GS}<V_T, there is a channel current even when the surface is not in strong inversion
- This subthreshold current
 - Due mainly to diffusion between and the channel
 - Becoming an increasing concern for deepsub-micron designs
- The model implemented in SPICE introduces an exponential, semi-empirical dependence of the drain current on V_{GS} in the weak inversion region

$$I_D(\text{weak inversion}) = I_{on} \cdot e^{(V_{GS} - V_{on}) \cdot \left(\frac{q}{nkT}\right)}$$

 I_{on} is the current in strong inversion for $V_{GS} = V_{on}$ the voltage V_{on} is found as

$$V_{on} = V_T + \frac{nkT}{q}$$
 where $n = 1 + \frac{q \cdot N_{FS}}{C_{ox}} + \frac{C_d}{C_{ox}}$

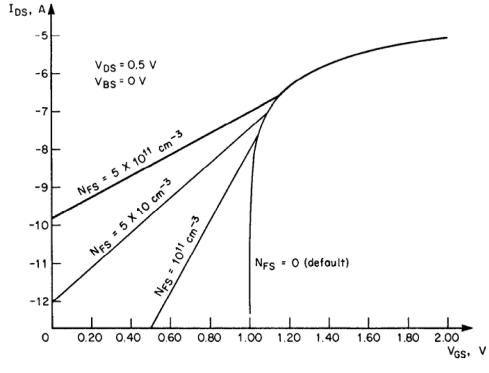


Figure 4.7 Variation of the drain current in the weak inversion region, as a function of the gate voltage and for different values of the parameter N_{FS} , in the LEVEL 2 model. (Copyright © 1988 by McGraw-Hill, Inc.)

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The parameter $N_{\it FS}$ is defined as the number of fast superficial states and is used as a fitting parameter that determines the slope of the subthreshold current - voltage characteristics

 C_d : is the depletion capacitance

This model introduces a discontinuity for $V_{GS} = V_{on}$, therefore, the simulation of the transition region between weak and strong inversion is not very precise

The LEVEL 3 model equations

- The LEVEL 3 model has been developed for simulation of short channel MOS transistor
 - Quite precisely for channel lengths down to 2μm
 - The current-voltage equation in the linear region has been simplified with a Taylor series expansion
 - The majority of the LEVEL 3 model equations are empirical
 - To improve the accuracy of the model
 - To limit the complexity of the calculation

$$I_{D} = \mu_{s} \cdot C_{ox} \cdot \frac{W}{L_{eff}} \cdot \left(V_{GS} - V_{T} - \frac{1 + F_{B}}{2} \cdot V_{DS}\right) \cdot V_{DS}$$

where
$$F_B = \frac{\gamma \cdot F_s}{4 \cdot \sqrt{|2\phi_F| + V_{SB}}} + F_n$$

The empirical parameter F_B express the dependence of the bulk depletion charge

The V_T . F_s , and μ_s are influenced by the short - channel effects

The F_n is influenced by the narrow - channel effects

$$\mu_s = \frac{\mu}{1 + \theta \cdot (V_{GS} - V_T)}$$

The decrease in the effective mobility with the average lateral electrical field

$$\mu_{eff} = \frac{\mu_s}{1 + \mu_s \cdot \frac{V_{DS}}{v_{\text{max}} \cdot L_{eff}}}$$



State-of-art MOSFET models

- BSIM-Berkeley short-channel IGFET model
 - The model is analytically simple and is based on a small number of parameters, which are normally extracted from experimental data
 - Accuracy and d\efficiency
 - Widely used by many companies and silicon foundries
- EKV (Enz-Krummenacher-Vittoz) transistor model
 - Previous models considering
 - The strong-inversion region of operation separately from the weakinversion region
 - Causing serous problems in the modeling of transistors at very low voltages as in many cases involving deep sub-micron CMOS technology
 - Attempting to solve this problem by
 - Using a unified view of the transistor operating regions
 - Avoiding the use of disjoint equations in strong and weak inversion



Gate oxide capacitance

- SPICE uses a simple gate oxide capacitance model that represents the charge storage effect by three nonlinear two-terminal capacitor: C_{GB} , C_{GS} and C_{GD}
- The geometry information required for the calculation of gate oxide capacitance are:
 - Gate oxide thickness TOX
 - Channel width W
 - Channel length L
 - Lateral diffusion LD
- The capacitances CGBO, CGSO, and CGDO, which are specified in the .MODEL statement, are the overlap capacitances between the gate and the other terminals outside the channel region
- If the parameter XQC is specified in the .MODEL statement
 - SPICE uses a simplified version of the charge-controlled capacitance model proposed by Ward

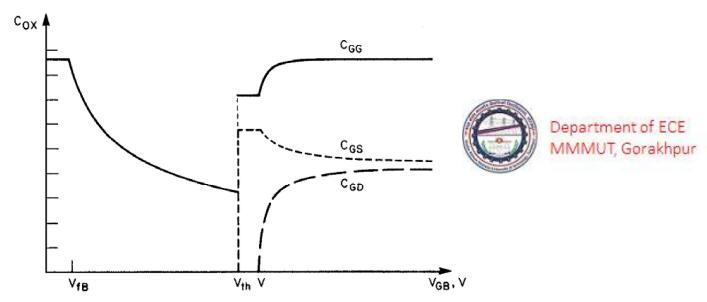


Figure 4.8 Oxide capacitances as functions of the gate-to-substrate voltage, according to Ward's capacitance model. (Copyright © 1988 by McGraw-Hill, Inc.)

Junction capacitance

$$C_{SB} = \frac{C_j \cdot AS}{\left(1 - \frac{V_{BS}}{\phi_0}\right)^{M_j}} + \frac{C_{jsw} \cdot PS}{\left(1 - \frac{V_{BS}}{\phi_0}\right)^{M_{jsw}}}$$

$$C_{DB} = \frac{C_j \cdot AD}{\left(1 - \frac{V_{BD}}{\phi_0}\right)^{M_j}} + \frac{C_{jsw} \cdot PD}{\left(1 - \frac{V_{BD}}{\phi_0}\right)^{M_{jsw}}}$$

C_i: the zero - bias depletion capacitance per unit area at the bottom of the junction

 C_{jsw} : the zero - bias depletion capzcitance per unit length at the sidewall junctions

$$C_{jsw} \cong \sqrt{10} \cdot C_j \cdot x_j$$

AS and AD are the source and the drain areas

PS and PD are the source and the drain perimeters

M_i and M_{isw} denote the junction grading coefficients for the bottom and the sidewalls junctions

Default values are $M_i = 0.5$ and $M_{isw} = 0.33$



Comparison of the SPICE MOSFET models

- The LEVEL 1 model
 - Not very precise
 - Quick and rough estimate of the circuit performance without much accuracy
- THE LEVEL 2 model
 - Require a larger time
 - May occasionally cause convergence problems in the Newton-Raphson algorithm used in SPICE
- THE LEVEL 3 model
 - The CPU time needed for model evaluation is less and the number of iterations are significantly fewer for the LEVEL three model
 - Disadvantage
 - The complexity of calculating some of its parameters

